ASSEMBLY NOTES: UNLESS OTHERWISE SPECIFIED
1. ALL COMPONENTS ARE RoHS COMPLIANT.
2. ALL THROUGH HOLE COMPONENTS MOUNTED ON THE TOP SIDE.
3. ALL COMPONENTS SHALL BE MOUNTED FLUSH TO THE BOARD.
4. ALL UNUSED COMPONENT PADS SHALL BE FREE OF SOLDER.
5. ALL LEADS SHALL BE TRIMMED TO A MAXIMUM LENGTH OF: N/A
6. MAXIMUM COMPONENT HEIGHT NOT TO EXCEED: N/A
7. THESE COMPONENTS REQUIRE SOCKETS: NONE.
8. UNPOPULATED COMPONENTS: SEE BILL OF MATERIALS.
9. FINISHED BOARD SHALL BE FREE OF ALL RESIDUES.
ASSEMBLY NOTES: UNLESS OTHERWISE SPECIFIED:

1. ALL COMPONENTS ARE ROHS COMPLIANT.
2. ALL THROUGH HOLES COMPONENTS MOUNTED ON THE TOP SIDE.
3. ALL COMPONENTS SHALL BE MOUNTED FLUSH TO THE BOARD.
4. ALL UNSOLDERED COMPONENTS SHALL BE FREE OF SOLDER.
5. ALL LEADS SHALL BE TRIMMED TO A MAXIMUM LENGTH OF: NA.
6. MAXIMUM COMPONENT HEIGHT NOT TO EXCEED: NA.
7. THESE COMPONENTS REQUIRE Sockets: NA.
8. UNPLUGGED COMPONENTS REAR BILL OF MATERIALS.
9. FINISHED BOARD SHALL BE FREE OF ALL RESIDUES.

assy layer

bottom silk
NOTES:
This PCB to be manufactured to meet all acceptance levels of a CLASS 2 PCB per ANSI/IPC-A-600G.
MATERIAL: Isola PCL370HR FR-4 or Equivalent.

Finished overall thickness: .062 inch
If board is multilayer, use black oxide on inner layers.

FINISH: □ Immersion Gold
□ Edge connector fingers shall be plated with Nickel/Gold, > 20 microinches gold.
□ FLASH Gold
□ Immersion Tin
□ Soldermask over bare copper (SMOBC) with Lead Free Hot-Air Leveled Solder (HALS).

Lead Free Hot-Air Leveled Solder (HALS).
Soldermask color: GREEN
Silkscreen color: White
All holes to be located by the coordinates from the NC drill data provided.
Use artwork set No. 05-07238 REV 1.0
Any alternatives to the above specifications must be approved by Microchip.
BOTTOM LAYER  BOTTOM SILK